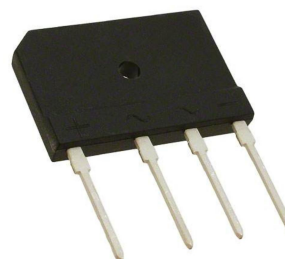
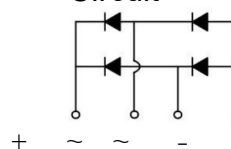


SINGLE-PHASE SILICON BRIDGE RECTIFIER
Features

- Glass passivated die construction
- Reverse Voltage - 100 to 1000Volts
- Ideal for printed circuit boards
- High surge current capability
- High temperature soldering guaranteed:
- 265°C/10 seconds, 0.375" (9.5mm) lead length, 5lbs. (2.3kg) tension
- Plastic material has U/L flammability classification 94V-0


Mechanical Data

- Case: Molded plastic case
- Terminals: Plated leads solderable per MIL-STD-750, Method 2026
- Polarity: Marked on Body
- Mounting position: Any
- specified. Single phase, half wave, 60Hz, resistive or inductive
- load. For capacitive load, derate current by 20%

Circuit

Maximum Ratings and Electrical Characteristics

- Rating at 25°C ambient temperature unless otherwise

TYPE NUMBER		SYMBOLS	GBJ 1001	GBJ 1002	GBJ 1004	GBJ 1006	GBJ 1008	GBJ 1010	UNIT
Maximum Reverse Peak Repetitive Voltage		V _{RRM}	100	200	400	600	800	1000	Volts
Maximum RMS Voltage		V _{RMS}	70	140	280	420	560	700	Volts
Maximum DC Blocking Voltage		V _{DC}	100	200	400	600	800	1000	Volts
Maximum Average Forward Rectified Output Current, 0.06”(1.5mm) lead length at		I _(AV)	10.0						Amps
Peak Forward Surge Current 8.3ms single half sine wave superimposed on rated load (JEDEC Method)		I _{FSM}	180						Amps
Rating for Fusing (t < 8.3ms)		I ² t	188						A ² s
Maximum Instantaneous Forward Voltage drop Per Bridge element 5.0A		V _F	1.0						Volts
Maximum Reverse Current at rated DC blocking voltage per element	TA=25°C	I _R	10						μAmps
	TA=125°C		500						
Typical Junction Capacitance Per Element ^{t(Note1)}		C _J	211			94			pF
Typical Thermal Resistance ^(NOTE 2)		R _{ΘJC}	4.3						°C/W
Mounting Torque (Recommended torque:0.5 N.m)		T _{OR}	0.8						N.m
Operating and Storage Temperature Range		T _J , T _{STG}	(-55 to +150)						°C

Notes:

1. Measured at 1.0MHz and applied reverse voltage of 4.0 Volts.
2. Junction to case with heatsink.
3. Recommended mounting position is to bolt down on heatsink with silicone thermal compound for maximum heat transfer with #6 screw.

Ratings and Characteristic Curves ($T_A=25^\circ\text{C}$ unless otherwise noted)

Fig.1- Forward Current Derating Curve

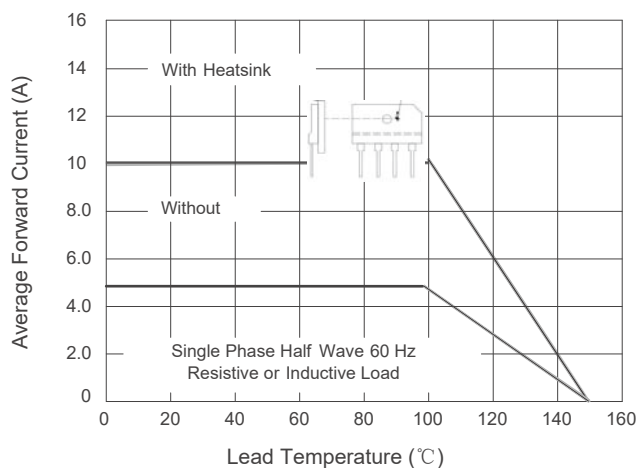


Fig. 2- Maximum Non-Repetitive Peak Forward Surge Current

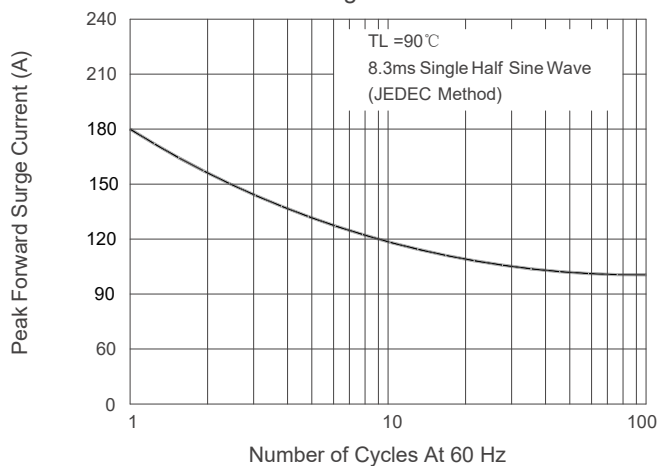


Fig.3-Typical Instantaneous Forward Characteristics

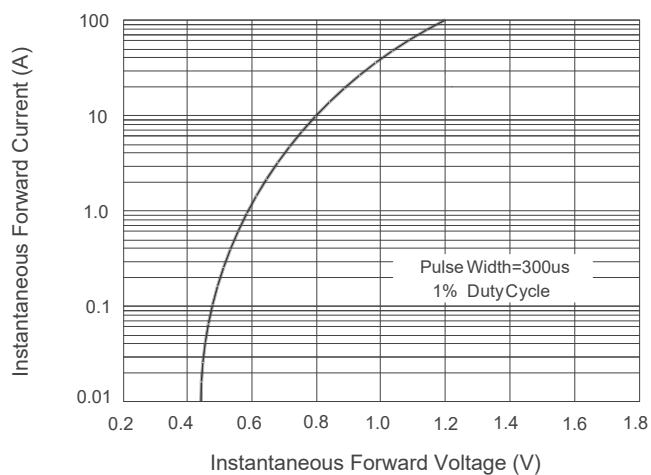


Fig. 4- Typical Reverse Characteristics

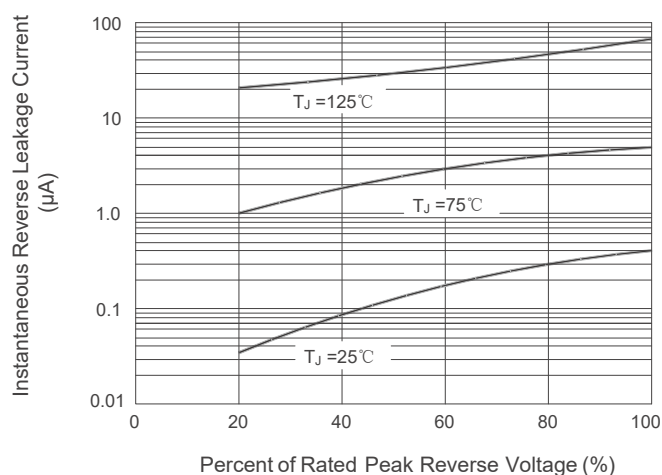
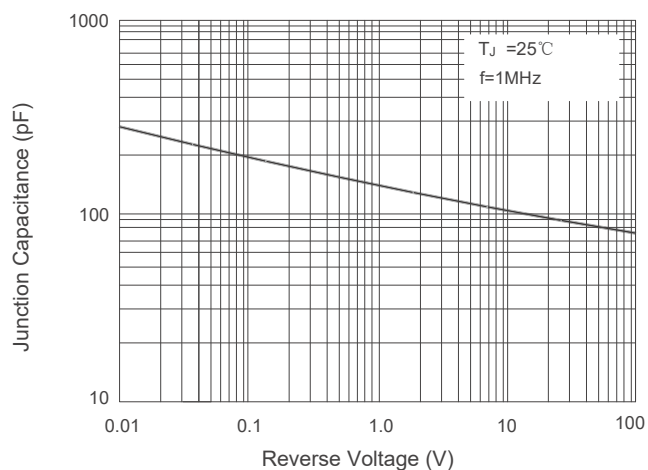
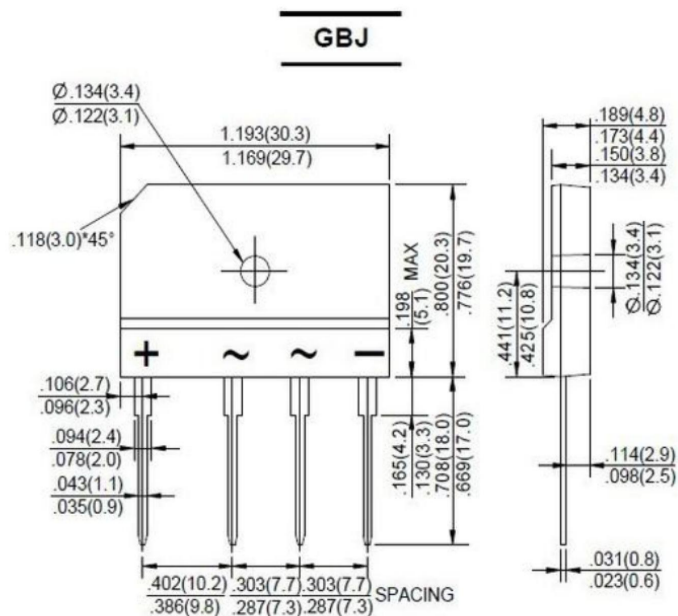


Fig.5- Typical Junction Capacitance



Package Outline Dimensions in inches (millimeters)

Ordering Information (Example)

PREFERED P/N	PACKING CODE	UNIT WEIGHT(g)	MINIIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON	DELIVERY MODE
GBJ	B1	Approximate 3.96	20	1000	2000	TUBE

Disclaimer

DACO Semiconductor reserves the right to make modifications, enhancements, improvements, corrections, or other changes to this document and any product described herein without prior notice. For the most up-to-date version, please visit our website.

DACO Semiconductor makes no warranty, representation, or guarantee regarding the suitability of its products for any particular purpose, nor does DACO Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any liability, including without limitation special, consequential or incidental damages.

Purchasers are responsible for its products and applications using DACO Semiconductor products, including compliance with all laws, regulations, and safety requirements or standards, regardless of any support or application information provided by DACO Semiconductor. "Typical" parameters that may be provided in DACO Semiconductor datasheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typical" must be validated for each customer application by the customer's technical experts.

DACO Semiconductor products are not designed, authorized, or warranted to be suitable for use in life support, life-critical or safety-critical systems, or equipment, nor in applications where failure or malfunction of DACO Semiconductor's product can reasonably be expected to result in personal injury, death or severe property or environmental damage. DACO Semiconductor accepts no liability for the inclusion and/or use of DACO Semiconductor's products in such equipment or applications and therefore such inclusion and/or use is at the customer's own risk.

Purchasers who buy or use DACO Semiconductor products for any unintended or unauthorized applications are required to indemnify and absolve DACO Semiconductor, its suppliers, and distributors from any claims, costs, damages, expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that DACO Semiconductor was negligent regarding the design or manufacture of the part.

No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or by any information storage and retrieval system, or otherwise, without the prior written permission of DACO Semiconductor Co., Ltd.